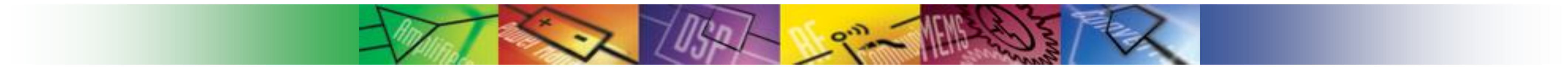

Product / Package Information

Package	LFCSP
Body Size (mm)	6 X 6 X 0.75 (4.3 EP)
Lead Count	40
Terminal Finish	100 Sn
MS Number	MS012668A

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.41E-02	87.00	870000	48.48	484776
Thermosets	Epoxy & Phenol Resin	628290-34-6	6.33E-03	12.50	125000	6.97	69652
Other inorganic materials	Carbon black	1333-86-4	2.53E-04	0.50	5000	0.28	2786
Subtotal			5.06 E-02	100.00	1000000	55.72	557213

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.28 E-02	97.5	975000	36.13	361293
Copper & its alloys	Iron	7439-89-6	7.91 E-04	2.35	23500	0.87	8708
Copper & its alloys	Zinc	7440-66-6	4.04 E-05	0.12	1200	0.04	445
Copper & its alloys	Phosphorus	7723-14-0	1.01 E-05	0.03	300	0.01	111
Subtotal			3.37 E-02	100.00	1000000	37.06	370557

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.37 E-05	100.0	1000000	0.04	371

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.15 E-03	100.0	1000000	2.37	23655

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	1.05 E-03	99.00	990000	1.15	11521
Precious metals	Palladium	7440-05-3	1.06 E-05	1.00	10000	0.01	116
Subtotal			1.06 E-03	100.00	1000000	1.16	11638

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.86 E-03	100.00	1000000	3.15	31494

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.96 E-04	84.00	840000	0.44	4358
Other organic materials	Epoxy Resin	9003-36-5 / 30583-72-3	5.66 E-05	12.00	120000	0.06	623
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-8	9.43 E-06	2.00	20000	0.01	104
Other organic materials	Phenolic hardener	92-88-6 / 26834-02-6	7.07 E-06	1.50	15000	0.01	78
Other organic materials	Butyl cellosolve acetate	112-07-2	2.36 E-06	0.50	5000	0.003	26
Subtotal			4.72 E-04	100.0	1000000	0.52	5188

	Weight (g)	Percentage (%)	PPM
Package Totals	**9.09 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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